

## DUAL P-Channel Enhancement Mode Power MOSFET

### Description

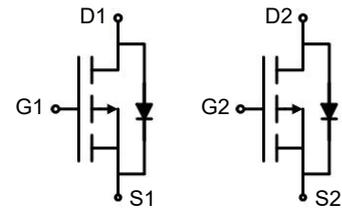
The G220P03D32 uses advanced trench technology to provide excellent  $R_{DS(ON)}$ , low gate charge. It can be used in a wide variety of applications.

### General Features

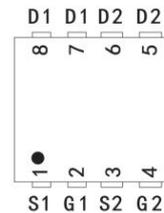
- $V_{DS}$  -30V
- $I_D$  (at  $V_{GS} = -10V$ ) -12A
- $R_{DS(ON)}$  (at  $V_{GS} = -10V$ ) < 22m $\Omega$
- $R_{DS(ON)}$  (at  $V_{GS} = -4.5V$ ) < 30m $\Omega$
- 100% Avalanche Tested
- RoHS Compliant

### Application

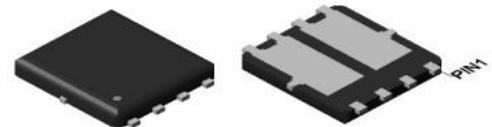
- Power switch
- DC/DC converters



Schematic diagram



pin assignment



DFN3X3-8L Dual

### Ordering Information

| Device     | Package        | Marking  | Packaging    |
|------------|----------------|----------|--------------|
| G220P03D32 | DFN3X3-8L Dual | G220P03D | 5000pcs/Reel |

### Absolute Maximum Ratings $T_C = 25^\circ\text{C}$ , unless otherwise noted

| Parameter  | Symbol         | Value      | Unit             |
|--|----------------|------------|------------------|
| Drain-Source Voltage                             | $V_{DS}$       | -30        | V                |
| Continuous Drain Current                         | $I_D$          | -12        | A                |
| Pulsed Drain Current (note1)                     | $I_{DM}$       | -48        | A                |
| Gate-Source Voltage                              | $V_{GS}$       | $\pm 20$   | V                |
| Power Dissipation                                | $P_D$          | 30         | W                |
| Single pulse avalanche energy (note2)            | $E_{AS}$       | 231        | mJ               |
| Operating Junction and Storage Temperature Range | $T_J, T_{stg}$ | -55 To 150 | $^\circ\text{C}$ |

### Thermal Resistance

| Parameter                               | Symbol     | Value | Unit                      |
|---|------------|-------|---------------------------|
| Thermal Resistance, Junction-to-Ambient | $R_{thJA}$ | 55    | $^\circ\text{C}/\text{W}$ |
| Maximum Junction-to-Case                | $R_{thJC}$ | 4.2   | $^\circ\text{C}/\text{W}$ |

| Specifications $T_J = 25^\circ\text{C}$ , unless otherwise noted |               |   |       |      |           |            |
|--|---------------|---|-------|------|-----------|------------|
| Parameter  | Symbol        | Test Conditions   | Value |      |           | Unit       |
|  |               |   | Min.  | Typ. | Max.      |            |
| <b>Static Parameters</b>   |               |   |       |      |           |            |
| Drain-Source Breakdown Voltage                                   | $V_{(BR)DSS}$ | $V_{GS} = 0V, I_D = -250\mu A$                            | -30   | --   | --        | V          |
| Zero Gate Voltage Drain Current                                  | $I_{DSS}$     | $V_{DS} = -30V, V_{GS} = 0V$                              | --    | --   | -1        | $\mu A$    |
| Gate-Source Leakage  | $I_{GSS}$     | $V_{GS} = \pm 20V$  | --    | --   | $\pm 100$ | nA         |
| Gate-Source Threshold Voltage                                    | $V_{GS(th)}$  | $V_{DS} = V_{GS}, I_D = -250\mu A$                        | -1.0  | -1.5 | -2.0      | V          |
| Drain-Source On-Resistance                                       | $R_{DS(on)}$  | $V_{GS} = -10V, I_D = -3A$                                | --    | 18   | 22        | m $\Omega$ |
|  |               | $V_{GS} = -4.5V, I_D = -3A$                               | --    | 25   | 30        |            |
| Forward Transconductance   | $g_{FS}$      | $V_{DS} = -3V, I_D = -6A$                                 | --    | 10   | --        | S          |
| <b>Dynamic Parameters</b>  |               |   |       |      |           |            |
| Input Capacitance  | $C_{iss}$     | $V_{GS} = 0V,$<br>$V_{DS} = -15V,$<br>$f = 1.0\text{MHz}$ | --    | 1305 | --        | pF         |
| Output Capacitance   | $C_{oss}$     |   | --    | 167  | --        |            |
| Reverse Transfer Capacitance                                     | $C_{rss}$     |   | --    | 163  | --        |            |
| Total Gate Charge  | $Q_g$         | $V_{DD} = -15V,$<br>$I_D = -3A,$<br>$V_{GS} = -10V$       | --    | 25   | --        | nC         |
| Gate-Source Charge   | $Q_{gs}$      |   | --    | 3    | --        |            |
| Gate-Drain Charge  | $Q_{gd}$      |   | --    | 6    | --        |            |
| Turn-on Delay Time   | $t_{d(on)}$   | $V_{DD} = -15V,$<br>$I_D = -3A,$<br>$R_G = 3\Omega$       | --    | 9    | --        | ns         |
| Turn-on Rise Time  | $t_r$         |   | --    | 8    | --        |            |
| Turn-off Delay Time  | $t_{d(off)}$  |   | --    | 26   | --        |            |
| Turn-off Fall Time   | $t_f$         |   | --    | 8    | --        |            |
| <b>Drain-Source Body Diode Characteristics</b>                   |               |   |       |      |           |            |
| Continuous Body Diode Current                                    | $I_S$         | $T_C = 25^\circ\text{C}$                                  | --    | --   | -12       | A          |
| Body Diode Voltage   | $V_{SD}$      | $T_J = 25^\circ\text{C}, I_{SD} = -3A, V_{GS} = 0V$       | --    | --   | -1.2      | V          |
| Reverse Recovery Charge  | $Q_{rr}$      | $I_F = -3A, V_{GS} = 0V$<br>$di/dt = -500A/\mu s$         | --    | 25   | --        | nC         |
| Reverse Recovery Time  | $T_{rr}$      |   | --    | 11.5 | --        | ns         |

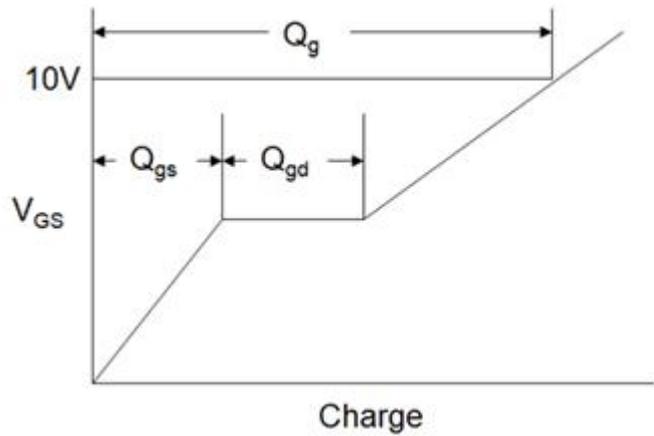
### Notes

1. Repetitive Rating: Pulse width limited by maximum junction temperature
2. EAS condition :  $T_J = 25^\circ\text{C}, V_{DD} = -30V, V_{GS} = -10V, L = 0.5\text{mH}, R_G = 25\Omega$

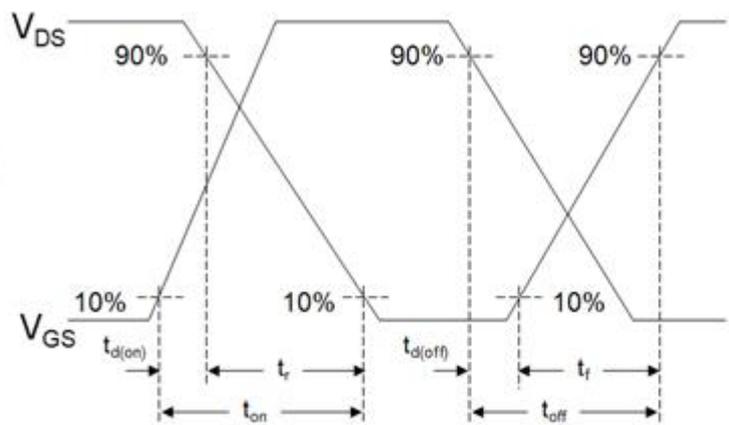
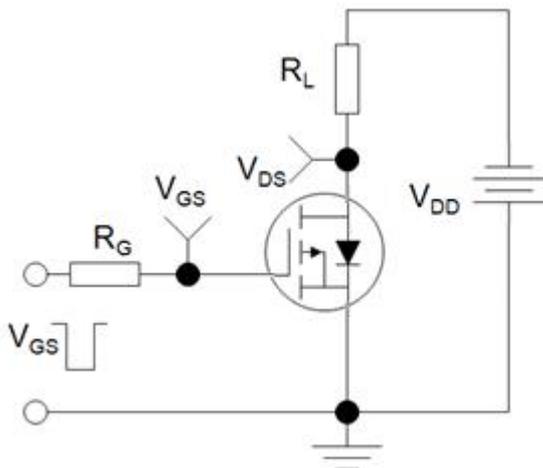
The table shows the minimum avalanche energy, which is 1444mJ when the device is tested until failure

3. Identical low side and high side switch with identical  $R_G$

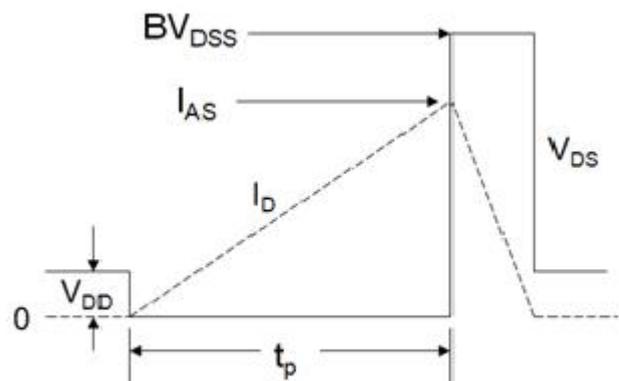
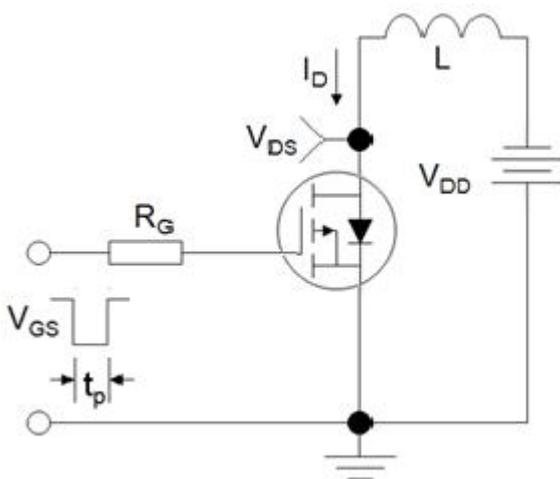
### Gate Charge Test Circuit



### Switch Time Test Circuit



### EAS Test Circuit



Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Figure 1. Output Characteristics

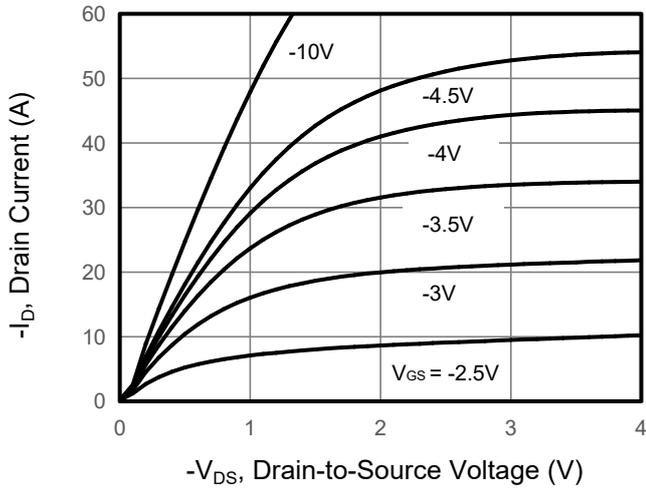


Figure 2. Transfer Characteristics

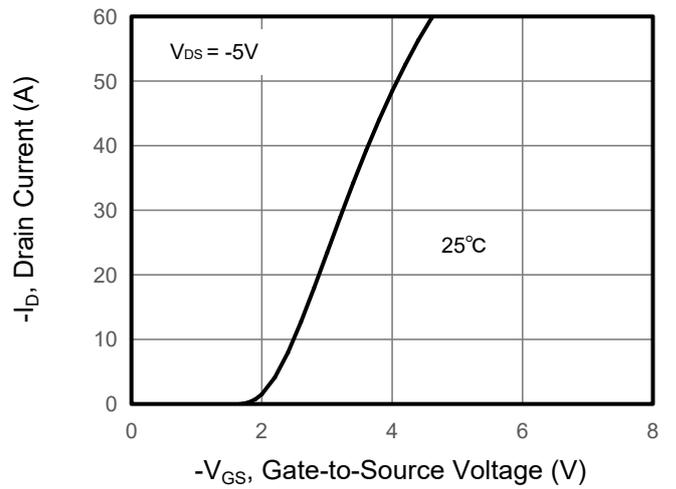


Figure 3. Drain Source On Resistance

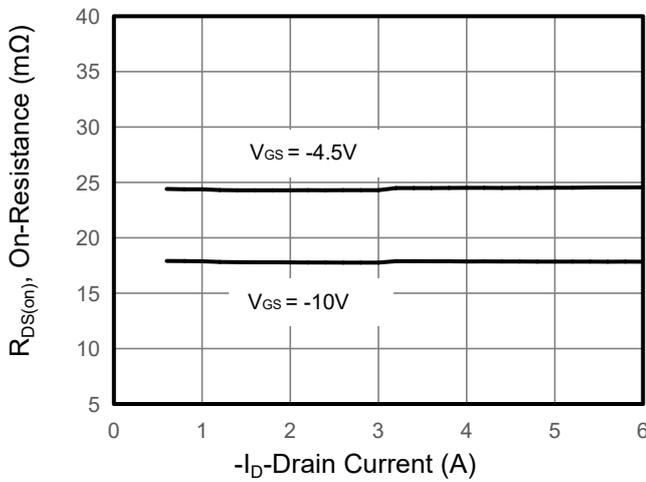


Figure 4. Gate Charge

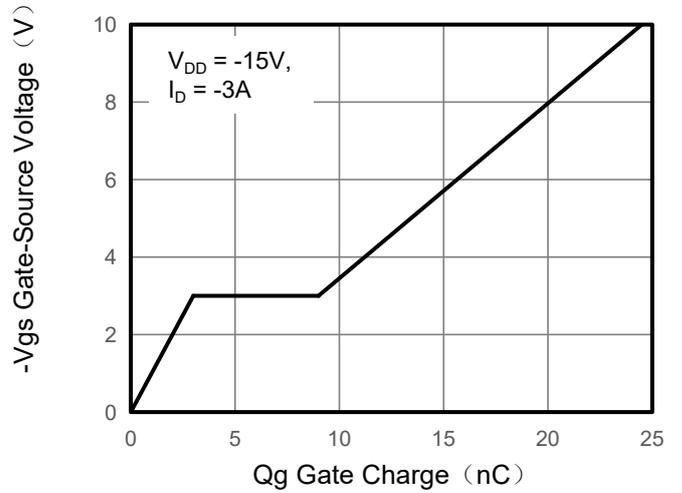


Figure 5. Capacitance

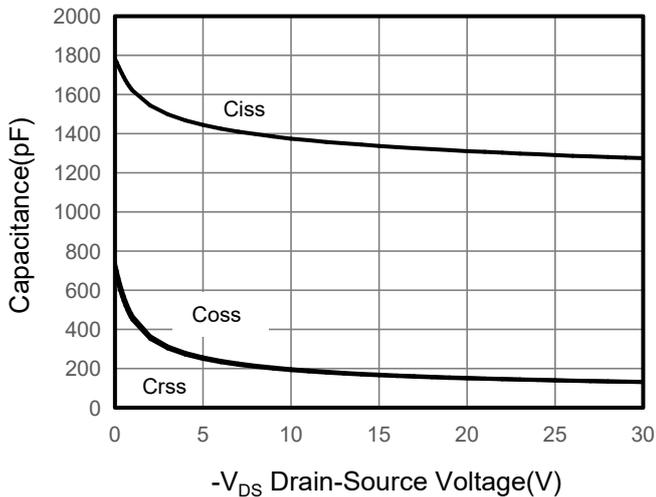
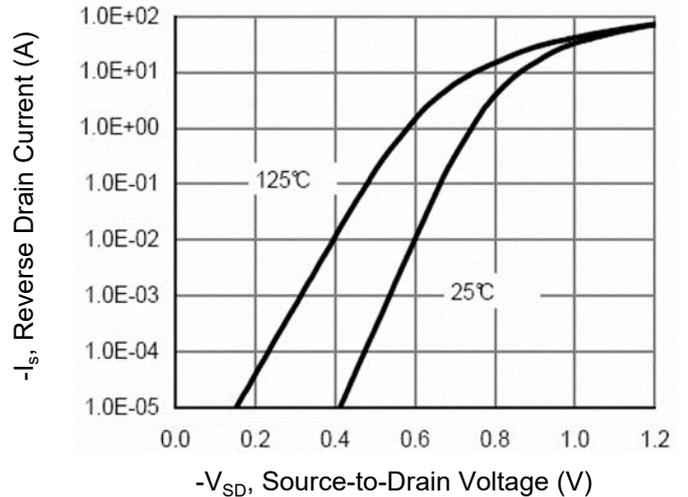


Figure 6. Source-Drain Diode Forward



Typical Characteristics  $T_J = 25^\circ\text{C}$ , unless otherwise noted

Figure 7. Drain-Source On-Resistance

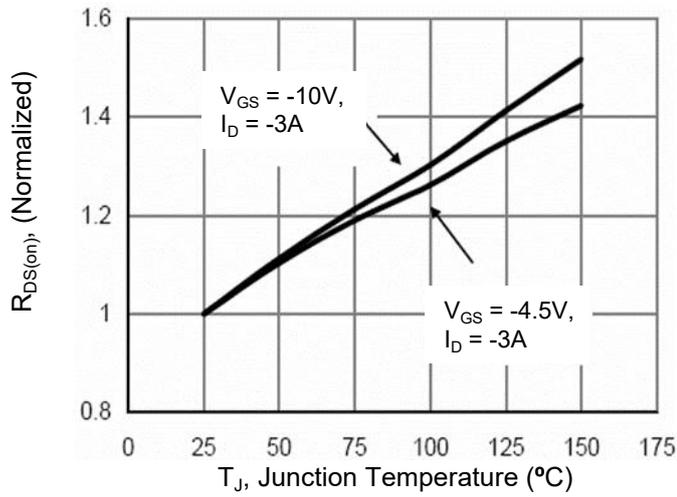


Figure 10. Safe Operation Area

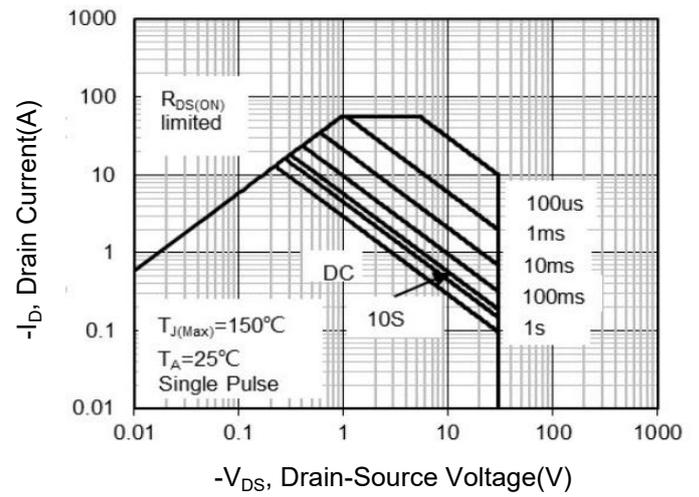
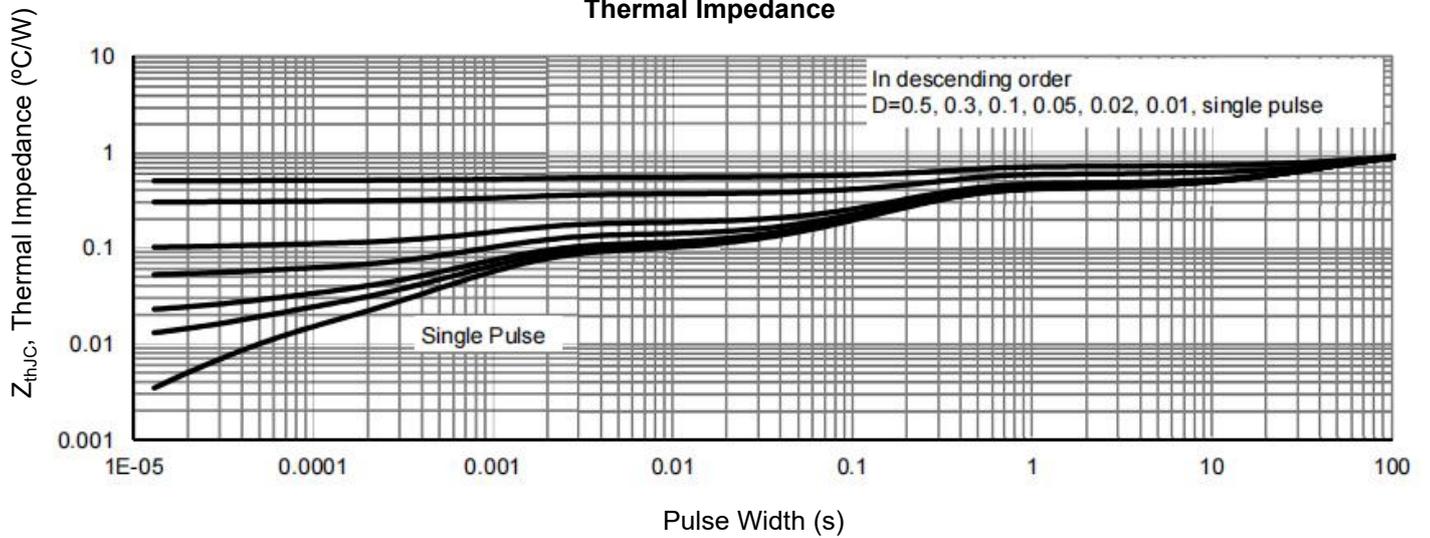
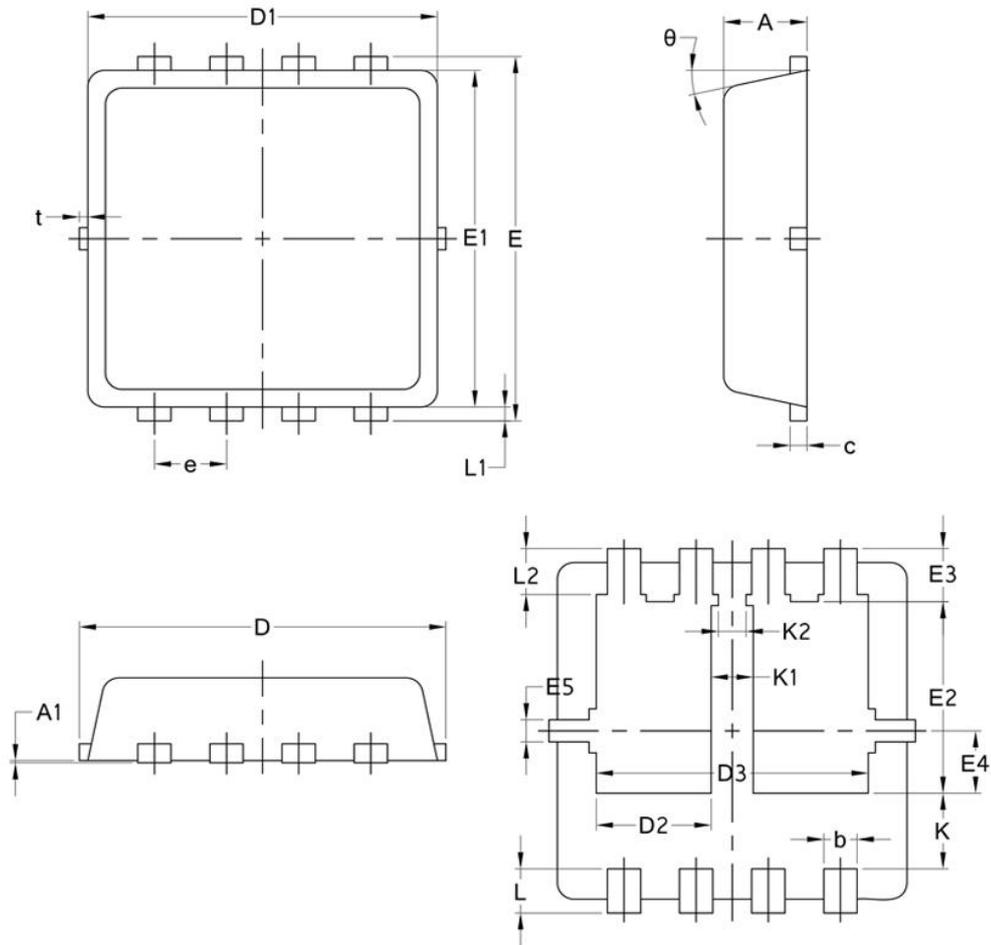


Figure 9. Normalized Maximum Transient Thermal Impedance



## DFN3\*3-8L Dual Package Information



| SYMBOL   | COMMON |       |      |    |      |       |      |
|----------|--------|-------|------|----|------|-------|------|
|          | MM     |       |      |    |      |       |      |
|          | MIN    | NOM   | MAX  | E2 | 1.60 | 1.74  | 1.90 |
| A        | 0.70   | 0.75  | 0.85 | E3 | 0.28 | 0.48  | 0.65 |
| A1       | /      | /     | 0.05 | E4 | 0.37 | 0.57  | 0.77 |
| b        | 0.25   | 0.30  | 0.39 | E5 | 0.10 | 0.20  | 0.30 |
| c        | 0.14   | 0.152 | 0.20 | e  | 0.60 | 0.65  | 0.70 |
| D        | 3.20   | 3.30  | 3.45 | K  | 0.50 | 0.69  | 0.80 |
| D1       | 3.05   | 3.15  | 3.25 | K1 | 0.30 | 0.38  | 0.53 |
| D2       | 0.84   | 1.04  | 1.24 | K2 | 0.15 | 0.25  | 0.35 |
| D3       | 2.30   | 2.45  | 2.60 | L  | 0.30 | 0.40  | 0.50 |
| E        | 3.20   | 3.30  | 3.40 | L1 | 0.06 | 0.125 | 0.20 |
| E1       | 2.95   | 3.05  | 3.15 | L2 | 0.27 | 0.42  | 0.57 |
| $\theta$ | 10°    | 12°   | 14°  | t  | 0    | 0.075 | 0.13 |